These assemblies are ESD sensitive, ESD precautions shall be observed.

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE  BOARD #: TIDA-01004  REV: E3  SUN REV: Not In VersionControl

IGNORE ->

PLOT NAME = Top Assembly Drawing  GENERATED : 1/9/2018 12:06:38 PM  TEXAS INSTRUMENTS
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

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